



Let Performance Drive

CMD183C4

7.5-13 GHz I/Q Mixer



Features

- ▶ Low conversion loss
- ▶ Low LO to RF, LO to IF leakages
- ▶ Image rejection: 26 dB
- ▶ Wide IF bandwidth
- ▶ Pb-free RoHs compliant 4x4 mm SMT package

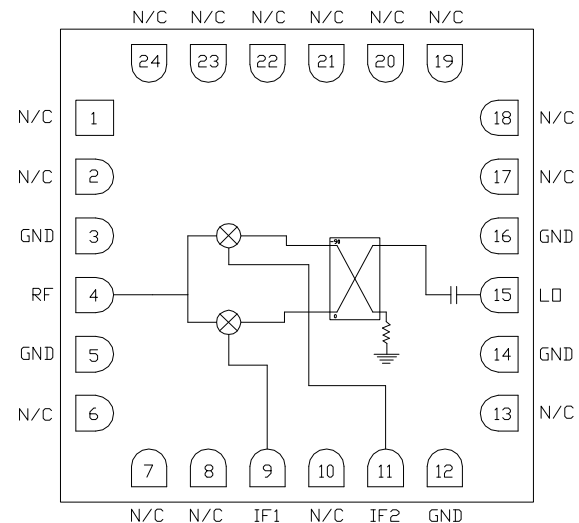
Description

The CMD183C4 is a compact I/Q mixer in a leadless surface mount package that can be used as either an image reject mixer or a single sideband upconverter. The CMD183C4 utilizes two double balanced mixer cells and a 90 degree hybrid. An external IF hybrid is needed to complete the image rejection. The CMD183C4 is a much smaller alternative to higher cost hybrid image reject mixers and single sideband upconverter assemblies.

Applications

- ▶ Point-to-point radios
- ▶ Point-to-multi-point radios
- ▶ Test Equipment & sensors
- ▶ Military end-use

Functional Block Diagram



Electrical Performance - IF = 100 MHz, LO = +15 dBm, T_A = 25 °C, F = 10 GHz

Parameter	Min	Typ	Max	Units
Frequency Range, RF & LO	7.5 - 13			GHz
Frequency Range, IF	DC		4.5	GHz
Conversion Loss (as IRM)		5.5		dB
Image Rejection		26		dB
LO to RF Leakage		-28		dBm
LO to IF Leakage		-8		dBm
Input P1dB		9		dBm

Unless otherwise noted, all measurements performed as a downconverter, IF = 100 MHz

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Specifications

Absolute Maximum Ratings

Parameter	Rating
RF / IF Input Power	+25 dBm
LO Drive	+25 dBm
Operating Temperature	-40 to 85 °C
Storage Temperature	-55 to 150 °C

Operation of this device outside the maximum ratings may cause permanent damage.

Electrical Specifications - IF = 100 MHz, LO = +13 dBm, T_A = 25 °C

Parameter	Min	Typ	Max	Min	Typ	Max	Units
Frequency Range, RF & LO	9 - 11			7.5 - 13			GHz
Frequency Range, IF	DC		4.5	DC		4.5	GHz
Conversion Loss (as IRM)		5.5	7		6	10	dB
Image Rejection	21	25		19	25		dB
LO to RF Leakage		-30	-22		-30	-22	dBm
LO to IF Leakage		-8	0		-8	0	dBm
Input P1dB		9			9		dBm

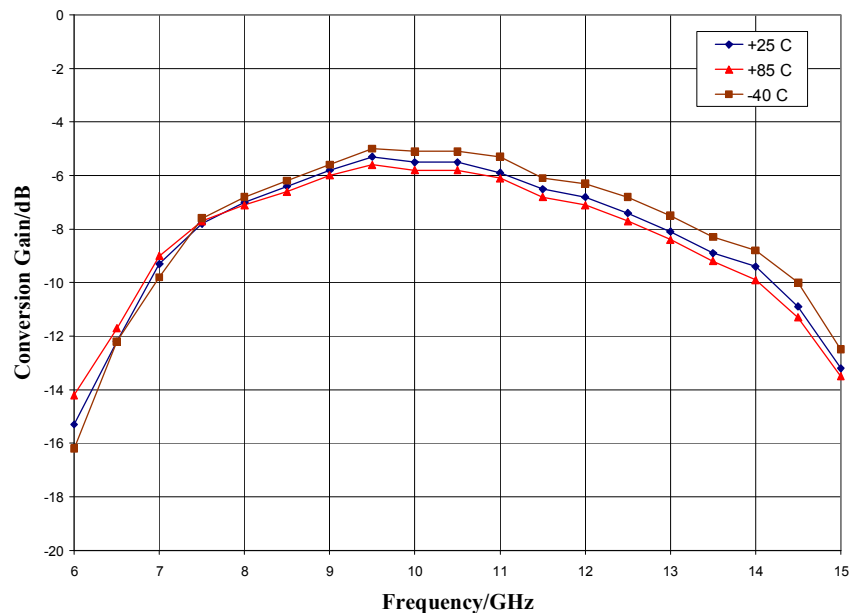
Unless otherwise noted, all measurements performed as a downconverter, IF = 100 MHz

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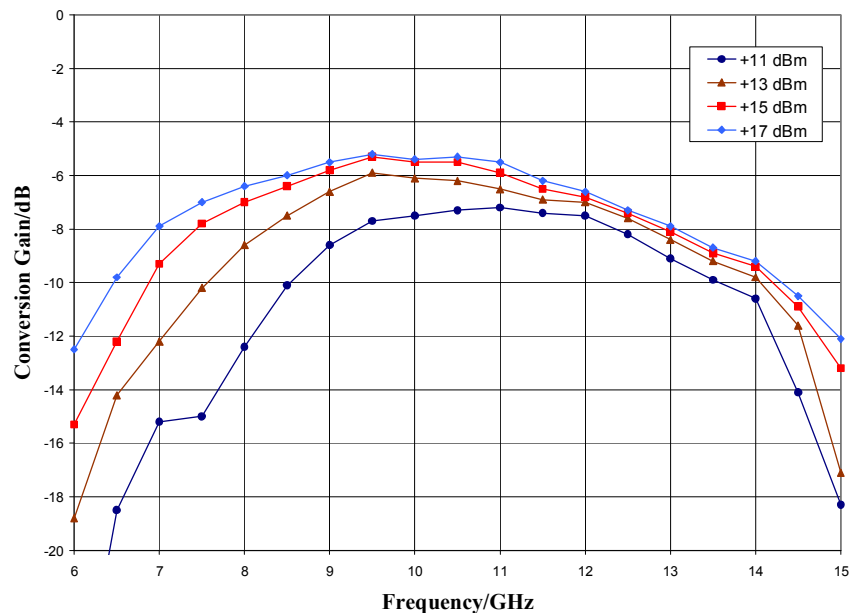
Typical Performance

Data Taken As IRM With External IF Hybrid

Conversion Gain vs. Temperature, LO = +15 dBm, IF = 100 MHz USB



Conversion Gain vs. LO Drive, IF = 100 MHz USB

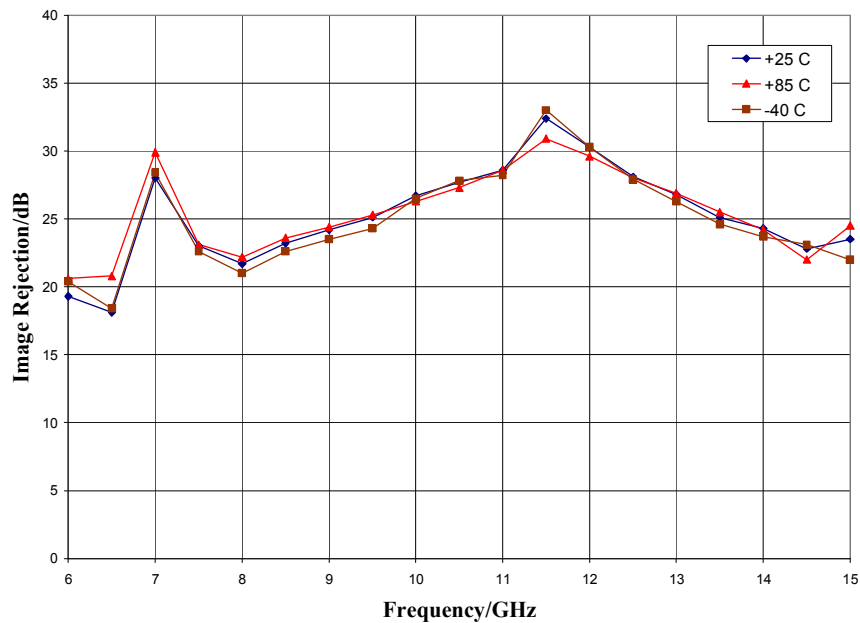


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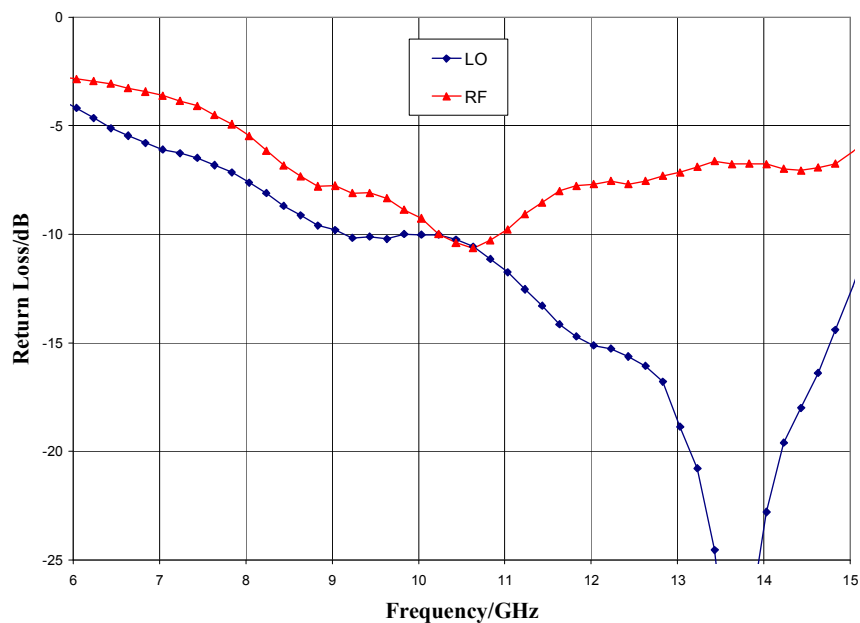
Typical Performance

Data Taken As IRM With External IF Hybrid

Image Rejection, LO = +15 dBm, IF = 100 MHz USB



Return Loss, LO = +15 dBm

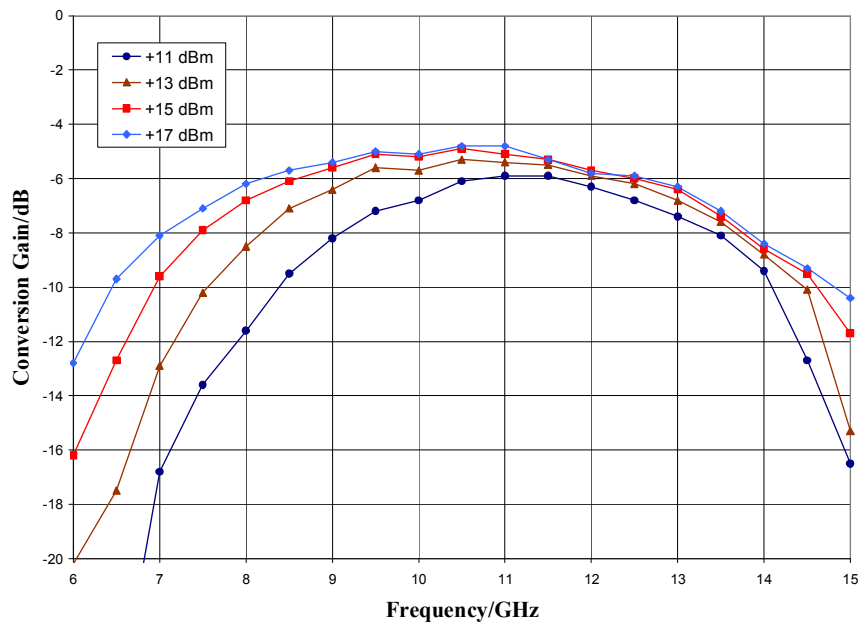


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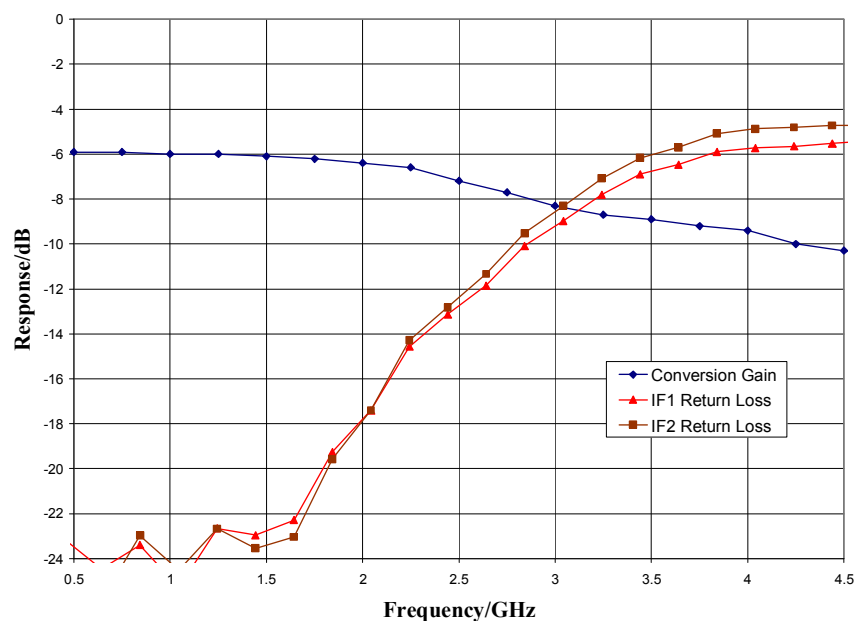
Typical Performance

Data Taken As IRM With External IF Hybrid

Upconverter Performance, Conversion Gain vs. LO Drive, IF = 100 MHz



IF Bandwidth, LO = +15 dBm, Return Loss Data Taken Without IF Hybrid

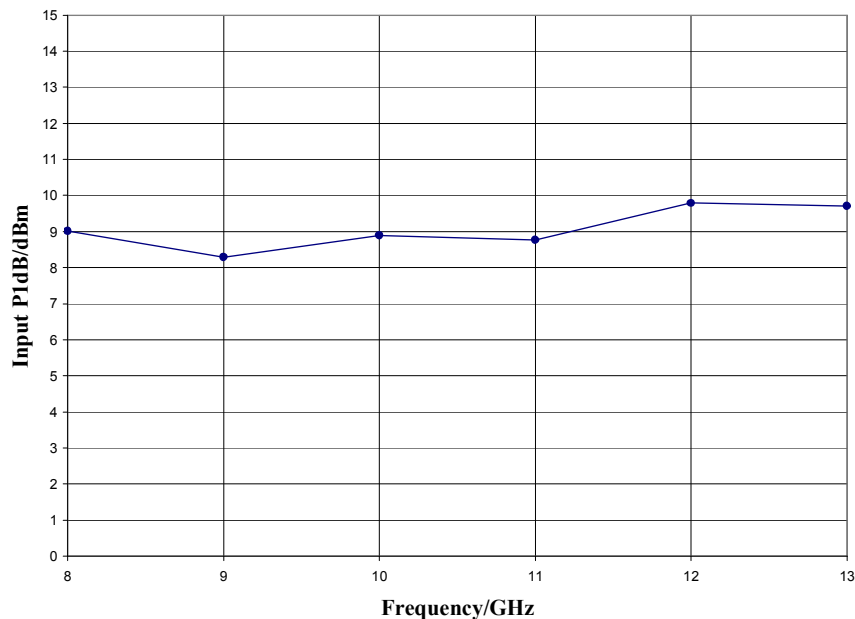


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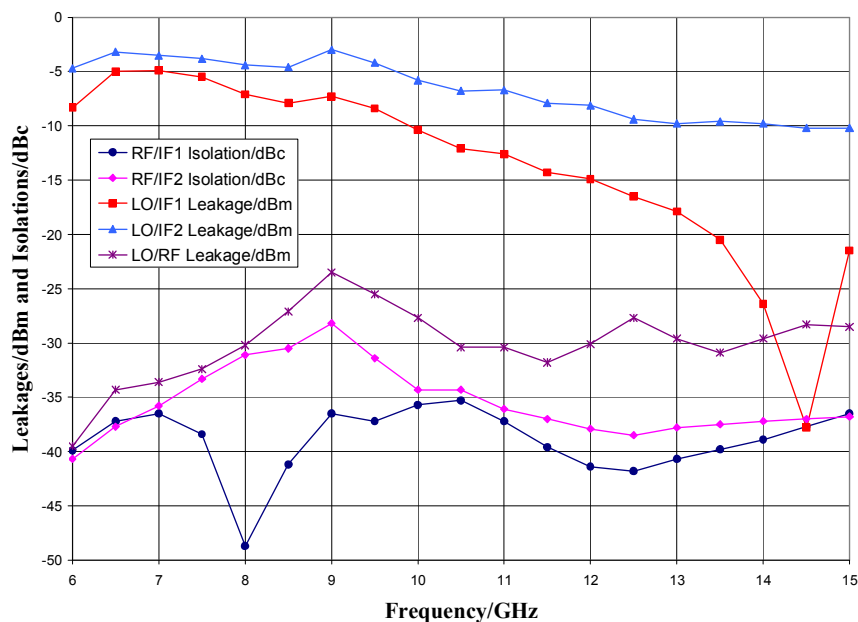
Typical Performance

Data Taken As IRM With External IF Hybrid

Input P1dB, LO = +15 dBm, IF = 100 MHz



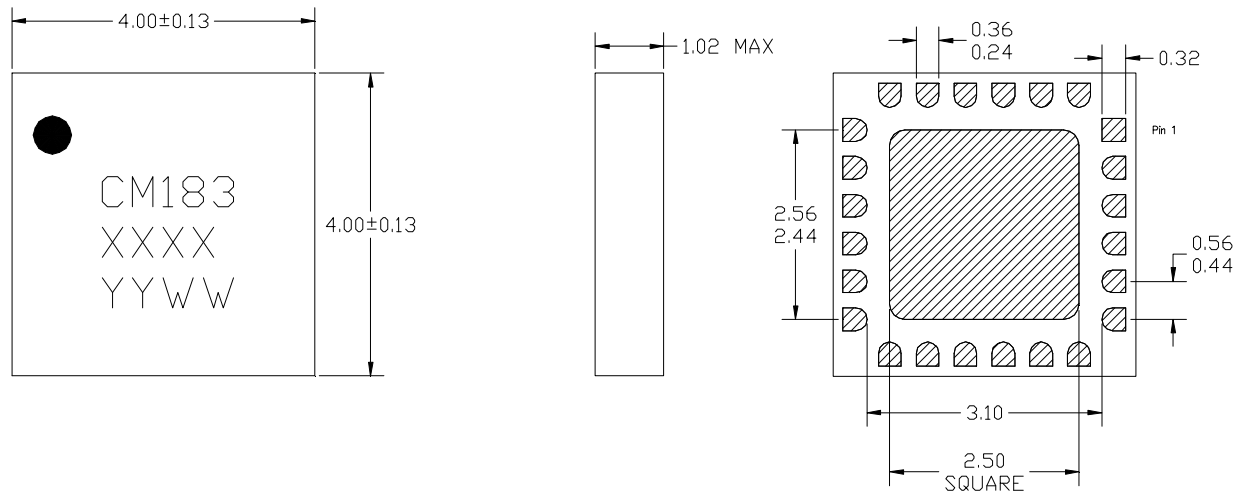
Leakages and Isolations, LO = +15 dBm. Data Taken Without IF Hybrid



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Mechanical Information

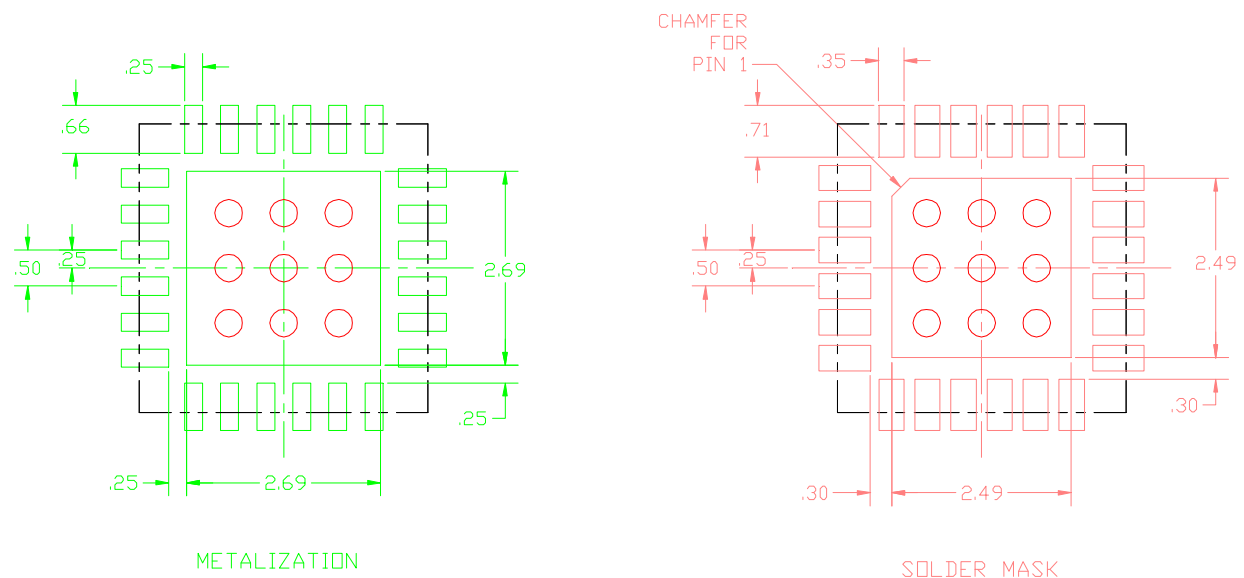
Package Information and Dimensions



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS
2. MATERIAL: BLACK ALUMINA
3. LEAD FINISH: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES NICKEL.
4. ALTERNATE PIN #1 IDENTIFIER IS SINGLE SQUARE PAD.

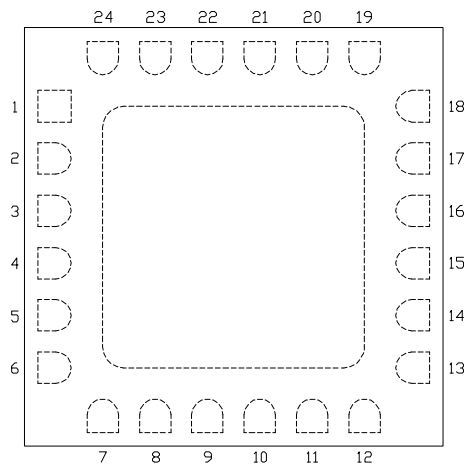
Recommended PCB Land Pattern



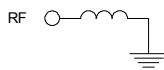
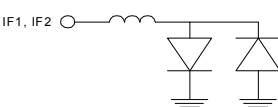
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Pin Description

Pin Diagram



Functional Description

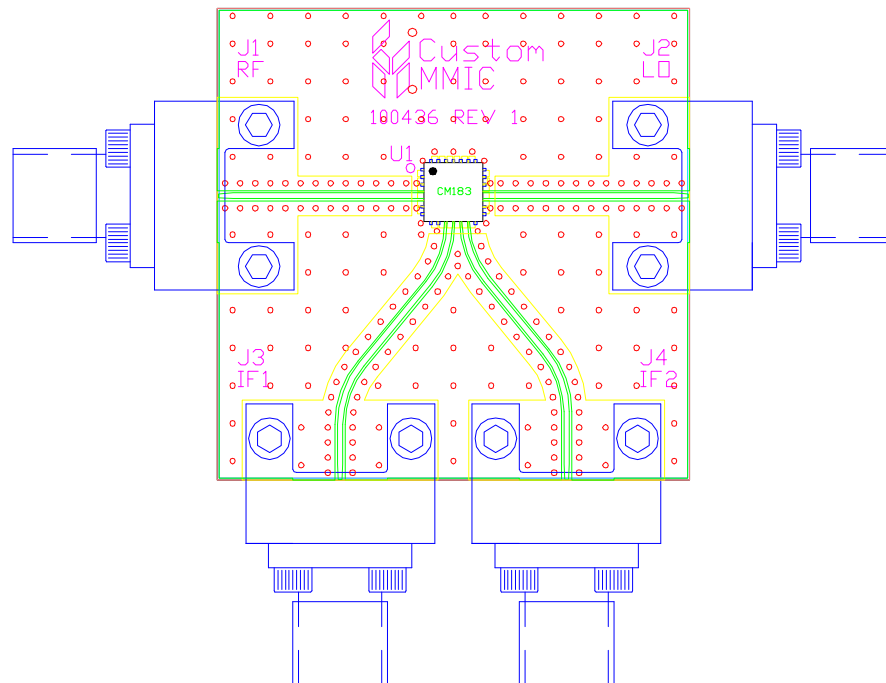
Pin	Function	Description	Schematic
1, 2, 6-8, 10, 13, 17-24	N/C	No connection required. These pins may be connected to RF/DC ground.	
3, 5, 12, 14, 16	Ground	Connect to RF / DC ground.	
4	RF	This pin is DC coupled and matched to 50 ohms.	
9	IF1	This pin is DC coupled. For applications not requiring operation to DC, this port should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary IF frequency range. For operation to DC, this pin must not source or sink more than 16 mA of current or part non-function or part failure may result.	
11	IF2		
15	LO	This pin is AC coupled and matched to 50 ohms.	

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Applications Information

Evaluation Board

The circuit board shown has been developed for optimized assembly at Custom MMIC. A sufficient number of via holes should be used to connect the top and bottom ground planes. As surface mount processes vary, careful process development is recommended.



Bill of Material

Designator	Value	Description
J1 - J4		SMA End Launch Connector
U1		CMD183C4 I/Q Mixer
PCB		100436 Evaluation PCB

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

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